

2ND AIDAINNOVA ANNUAL MEETING RECENT RESULTS ON IRRADIATED LF-MONOPIX2

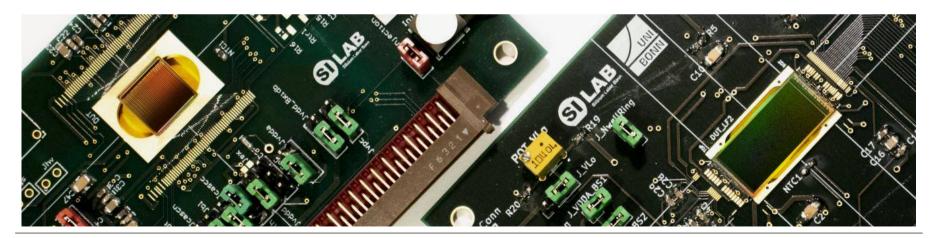
Lars Schall on behalf of the LF-Monopix testing team

Lars Schall – 2nd AIDAinnova Annual Meeting

25.04.23



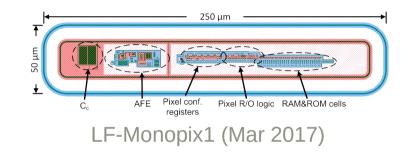
- The LF-Monopix Chips
- Laboratory test of irradiated LF-Monopix2
- Testbeam results of irradiated LF-Monopix2
- Conclusion and upcoming plans

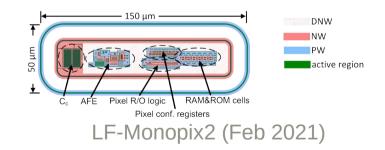




The LF-Monopix Chips

- 150nm LFoundry CMOS Technology
- Large collection electrode design
- Substrate resistivity > 2 kΩcm
- Fast column drain readout architecture (FE-I3 like)
- Full in-pixel R/O electronics
- LF-Monopix1:
 - ~1x1 cm² matrix
 - 50x250 μm² pixel pitch
- LF-Monopix2:
 - ~2x1 cm² matrix
 - 50x150 μ m² pixel pitch

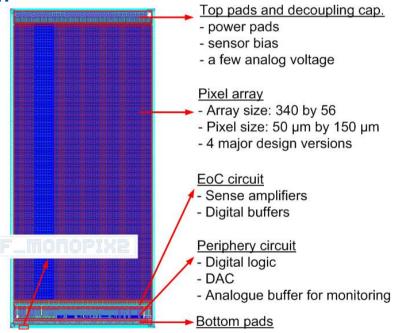






LF-Monopix2: Design

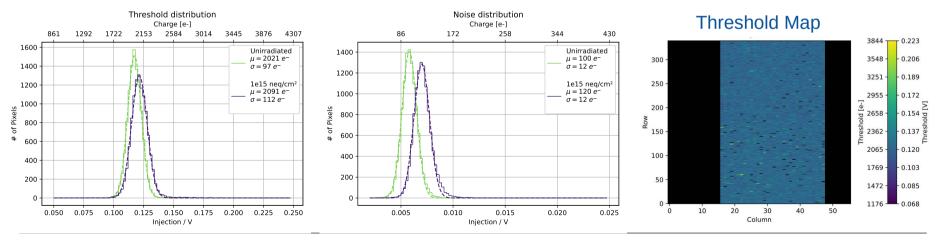
- Column drain readout architecture and full column length
 - Improved pixel layout to mitigate cross-talk
- Total of 6 matrices with 3 CSA types
 - Largest matrix with proven FE design from LF-Monopix1
- 6 bit ToT information
- 4 bit in-pixel threshold DAC
 - Two different tuning circuit designs
- Wafers successfully thinned down to 100 μm and backside processed





Laboratory Tests

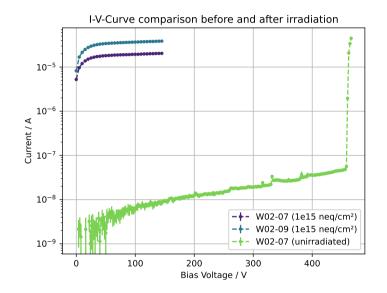
- Available fluences unirr | 1e15 neq/cm² | 2e15 neq/cm² (lab tests ongoing)
 - **Proton irradiation**: 1e15 at Bonn cyclotron, 2e15 at Birmingham MC40 cyclotron
- Operate irradiated chips at -20°C, unirr at room temperature
- Able to tune to approx. 2ke⁻ threshold and ~100e⁻ dispersion after irradiation
 - 20% increase in ENC after irradiation to 1e15 neq/cm²





I-V-Curves

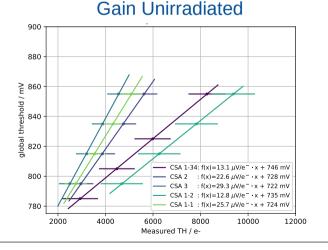
- Breakdown voltage between 450 500V for unirradiated chips
- Expected increase in leakage current after irradiation
 - Unirradiated @ room temperature
 - Irradiated 1e15 neq/cm² @ -15°C
 - No temperature scaling done here
- Difference after irradiation still under investigation

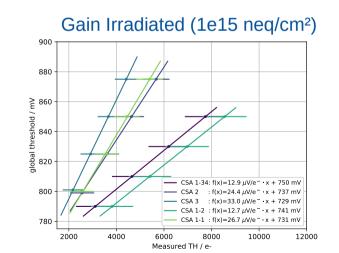




Gain Measurements

- · Measure untuned threshold at different global threshold settings
 - Gain extracted from linear regression
 - Smaller $C_{feedback} \rightarrow larger gain \rightarrow faster LE rise time$
- Gain slightly increased for large gain matrices after irradiation



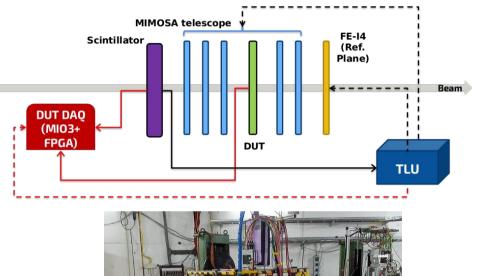




Testbeam Setup

- DESY: 5 GeV electron beam
- Telescope setup:
 - Scintillator
 - EUDET type beam telescope
 - FE-I4
 - Trigger Logic Unit (TLU)
 - DUT (LF-Monopix2)
- Irradiated DUT cooled to -20°C
- Sample Scintillator, DUT hit, TLU trigger in DAQ for event building

Following TB results measured with a 1e15 neq/cm² irradiated chip

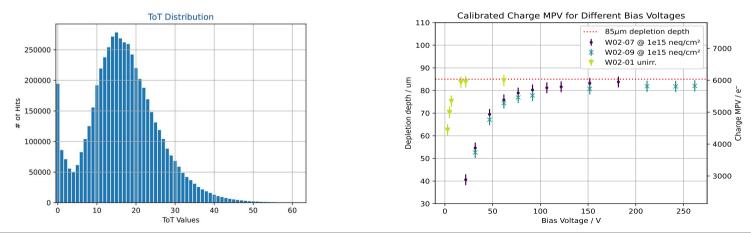






Depletion Depth

- All chips operated at roughly 2ke⁻ threshold
- Calculate calibrated charge MPVs from ToT distribution
- Depletion depth profile of 1e15 irradiated chips in very good agreement
 - Full depletion reached around 120V bias @ 1e15 neq/cm²
 - ~15V for unirradiated chips



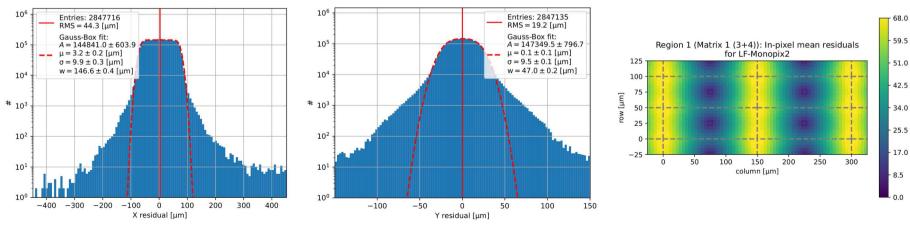




- Testbeam analysis done using *Beam Telescope Analysis*
- Residuals as expected
- Fitted Box-Gaussian to distribution •

Local X residuals

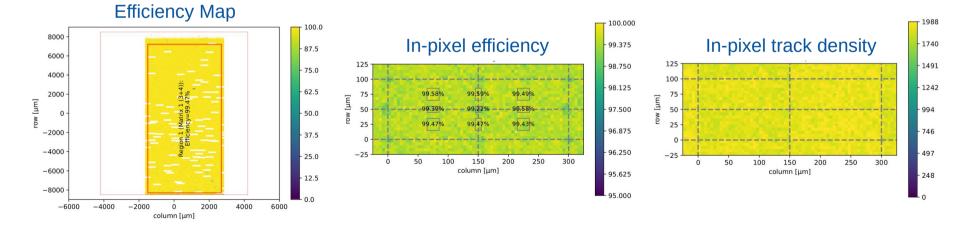
Box width in good agreement with pixel pitch (150 x 50 μ m²) •



Local Y residuals



- Uniform hit detection and in-time efficiency across matrix (150V bias, 2ke- threshold)
 - Data run shown here $(99.5 \pm 0.1)\%$ hit detection efficiency
- Projected onto 2x2 in-pixel plots for in-pixel studies
- Combine data runs to achieve higher statistics (if necessary)





Efficiency Results

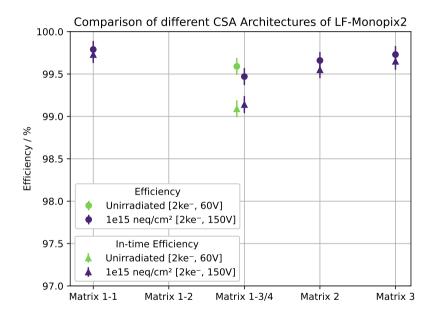
<u>1e15 neq/cm²:</u>

 Hit detection and in-time efficiencies > 99% at 2ke⁻ threshold and 150V bias voltage

2e15 neq/cm²:

- Problems with cooling setup
- Could not reach reasonable threshold
- Large increase in leakage current
- But could talk to chips continuously

Unirradiated result at 2ke⁻ threshold and 60V bias voltage as comparison



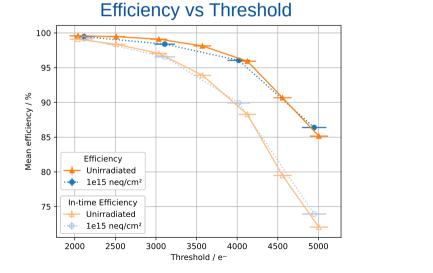
- \rightarrow No significant efficiency loss after irradiation to 1e15 neq/cm²
- → No stable operation possible at latest testbeam with 2e15 neq/cm² irradiated chips



Efficiency Threshold and Bias Run

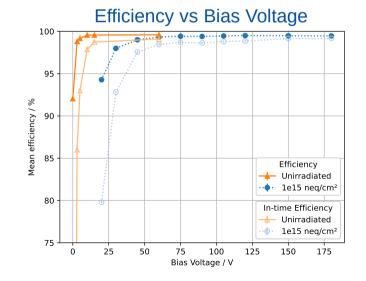
Efficiencies at different thresholds:

 Decrease in efficiency for higher thresholds



Efficiencies at different bias voltages:

• Increase in efficiency for higher bias voltages until full depletion of sensor



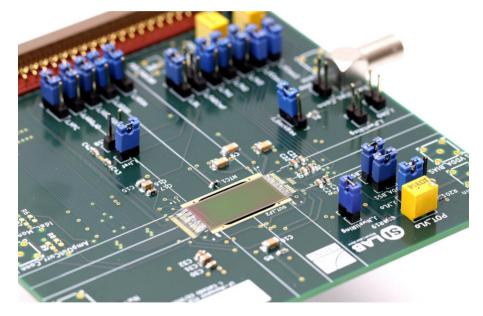


Conclusion and Outlook

- LF-Monopix2 fully functional and efficient after irradiation to 1x10¹⁵ neq/cm²
 - Measured hit detection efficiencies
 > 99% for all FE designs
- Cooling setup and leakage current problems lead to difficulties at testbeam with 2x10¹⁵ neq/cm² irradiated chips

Upcoming:

- Detailed lab tests with 2e15 neq/cm² irradiated sensor
 - Check possible leakage current issues
- TID irradiation campaign





Thank you for your attention!

The measurements leading to these results have been performed at the Test Beam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF)

This project has received funding from the European Union's Horizon 2020 Research and Innovation programme under GA No. 675587-STREAM, 654168 (AIDA-2020) and 101004761 (AIDA-Innova)



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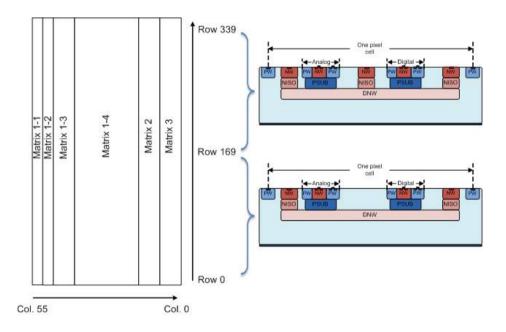




Backup



LF-Monopix2 In-Pixel Design



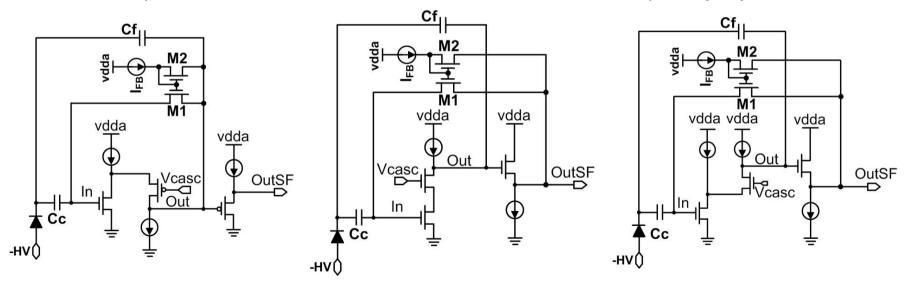
Matrix	Column	CSA	Feedback cap.	Discriminator	Logic
1-1	55 - 52	V1	$1.5\mathrm{fF}$	Bidirectional tuning	Falling
1-2	51 - 48	V1	$5\mathrm{fF}$	Bidirectional tuning	Falling
1-3	47 - 40	V1	$5\mathrm{fF}$	unidirectional tuning	Rising
1-4	39 - 16	V1	$5\mathrm{fF}$	unidirectional tuning	Falling
2	15 - 8	V2	$1.5\mathrm{fF}$	Bidirectional tuning	Falling
3	7 - 0	V3	$1.5\mathrm{fF}$	Bidirectional tuning	Falling



CSA Types of LF-Monopix2

CSA 1 NMOS amplifier from LF-Monopix1

CSA 2 Telescopic cascaded structure CSA 3 Current into input transistor from two separately adjustable branches



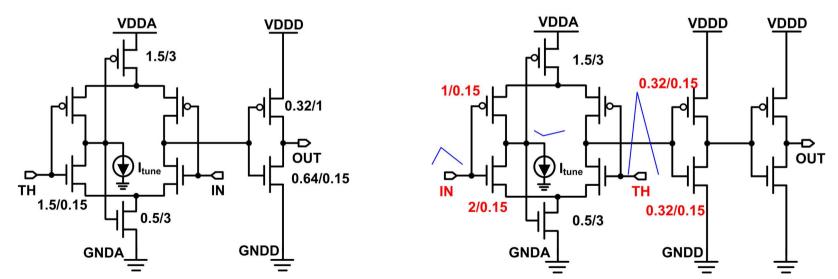


Discriminator Types of LF-Monopix2

Unidirectional Self-biased differential amplifier followed by a CMOS inverter

Bidirectional

Optimized transistor dimensions and swapped input ports for faster speed

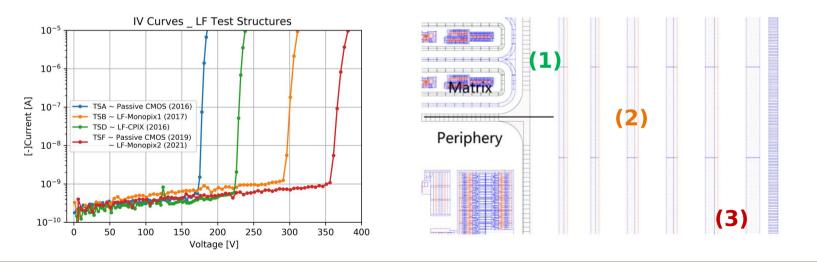




LF-Monopix: Guard Ring Design

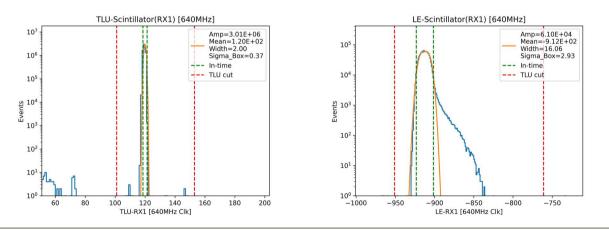
Improvement of breakdown voltage achieved by:

- Adding Deep N-well on innermost n-ring (1)
- P+N combination in guard-rings (2)
- Reduction of guard-ring number -> Increase in spacing (3)





- 1. Match TLU640 with closest Scintillator and TLU timestamp in raw data
- 2. Look for most frequent frequent value and cut on it (both LF-Monopix2 and FE-I4 data)
- 3. Match TLU640 with closest DUT hit (leading edge) timestamp
- 4. Assign corresponding Scintillator timestamp to DUT hit

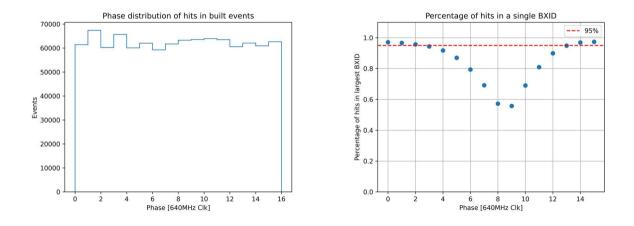




- LF-Monopix2 is triggerless
- Leading edges (LE) sampled at 40MHz (25ns)
- Look at the matched scintillator signals (640 MHz), and find the **time frame where most hits have its leading edge in a single BCID.**

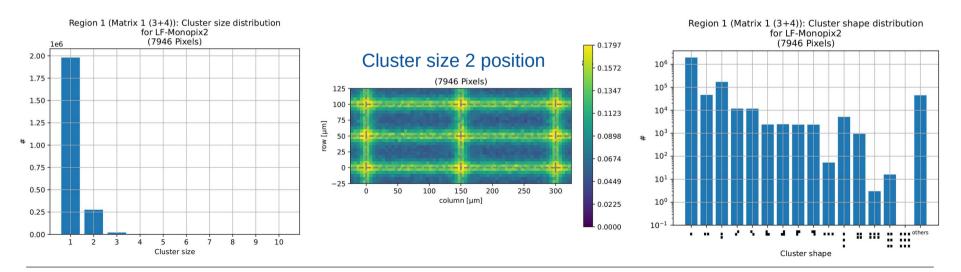


- Events are equally likely to come at any time within a single BCID
- Look at each 640MHz clock within 25ns and quantify percentage of hits in single BCID
- Take events of highest percentage hits in single BCID to analyze **in-time efficiency**
 - Due to jitter of TLU also take the phase before and after into account





- Mostly observe single pixel clusters
- Charge sharing likely at pixel edges
- Vertical clusters more likely than horizontal clusters (pixel shape)





In-Pixel Efficiency for Non-Optimal Operation

- Efficiency loss most prominent in pixel corners (expected)
 - Significant efficiency loss (<96%) already present at:
 - → 3ke⁻ mean treshold @ 150V bias voltage
 - → 45V bias voltage @ 2ke⁻ mean threshold

